

NON-PROVISIONAL APPLICATION FOR U. S. PATENT AND  
TRANSMITTAL FORM

CFR 1.53(b)

Attorney Docket No. TI-26059

Assistant Commissioner for Patents  
Washington, D. C. 20231

Sir:

Transmitted herewith for filing is the  
patent application of:

Inventor(s): Katherine G. Heinen  
Darvin R. Edwards  
Elizabeth G. Jacobs

"EXPRESS MAILING" Mailing Label No.  
EE528827016US. Date of Deposit: November 5, 1998. I  
hereby certify that this paper is being deposited with the  
U.S. Postal Service Express Mail Post Office to Addressee  
Service under 37 CFR 1.10 on the date shown above and is  
addressed to the Assistant Commissioner for Patents,  
Washington, D.C. 20231.

*Lynnda Van Deventer*  
Lynnda Van Deventer

U.S. PTO  
09/186973  
11/05/98

For: Wafer-Scale Assembly of Chip-Size Packages

Enclosed are:

- 6 sheets of informal drawings and 20 pages of Specification (including Abstract)  
x A Declaration/Power of Attorney  
x Assignment with form PTO 1595

Please amend the specification by inserting before the first line the sentence:

This application claims priority under 35 USC § 119 (e) (1) of provisional application number 60/066,256,  
filed 11/20/97.

FEE CALCULATION					FEE
	NUMBER		NUMBER EXTRA	RATE	BASIC FEE \$ 790.00
Total Claims	18	-20 =	0	X \$22 =	\$0.00
Independent Claims	4	- 3 =	1	X \$82 =	\$82.00
Total Filing Fee					\$872.00

Please charge Deposit Account No. 20-0688 in the amount of the Total Fees set forth. The Commissioner is hereby  
authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No.  
20-0688. This form is submitted in triplicate.

All correspondence related to this application may be addressed to the undersigned at Klinger & Navarro, L.L.P. 801  
E. Campbell Rd. Suite 655, RICHARDSON, TX 75081.

Date: November 5, 1998

*Gary C. Honeycutt*  
Gary C. Honeycutt  
Registration No. 20,250

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November 5, 1998

**VIA EXPRESS MAIL EE528827016US**

Assistant Commissioner for Patents  
Washington, D.C. 20231

Re: Patent Application For:

**WAFER-SCALE ASSEMBLY OF CHIP-SIZE PACKAGES**

Our File: 1000-2035

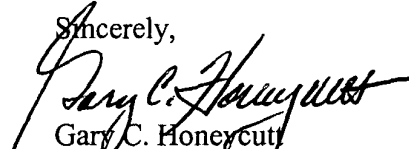
Dear Sir:

Enclosed for filing please find the following items relating to the above-identified application:

- (1) Original Patent Application and Drawings;
- (2) Original Assignment, Declaration, and Power of Attorney;
- (3) Assignment Recordation Form Cover sheet - Form PTO-1595;
- (4) Application Transmittal form; and
- (5) Postcards.

Please file the application and return the date-stamped postcard to the corresponding addresses as indicated. In the meantime, if you have any questions or comments concerning this matter, please call the undersigned. Otherwise, please accept the enclosed.

Sincerely,



Gary C. Honeycutt  
Registration No. 20,250

GCH/lcv  
Enclosure

cc: Warren Franz  
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